

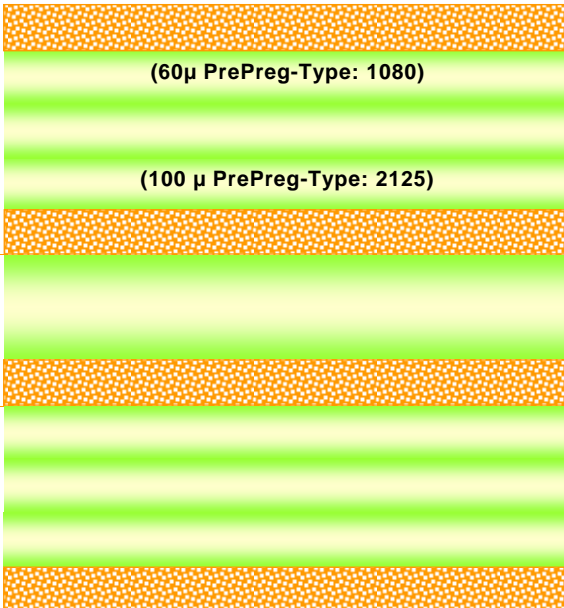
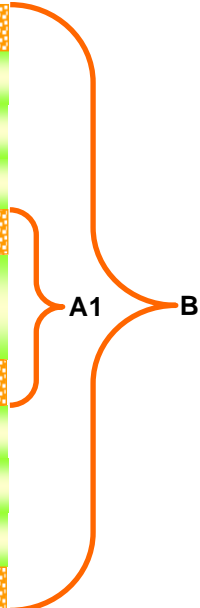
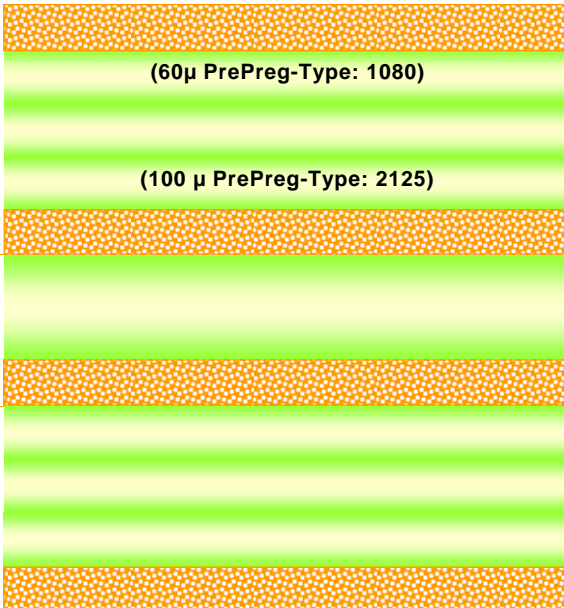
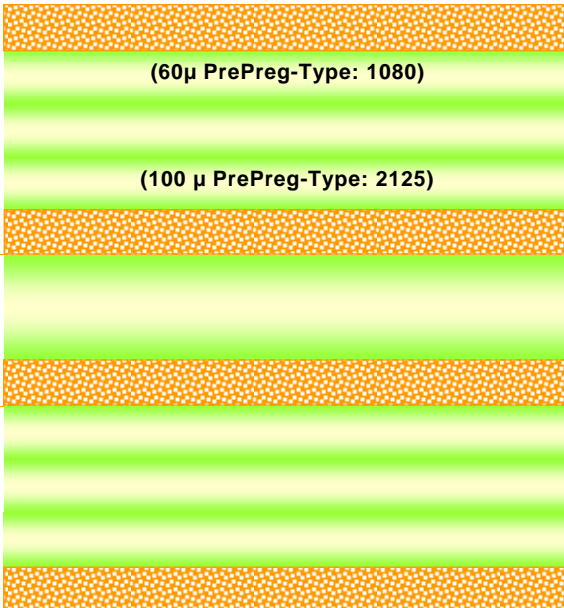
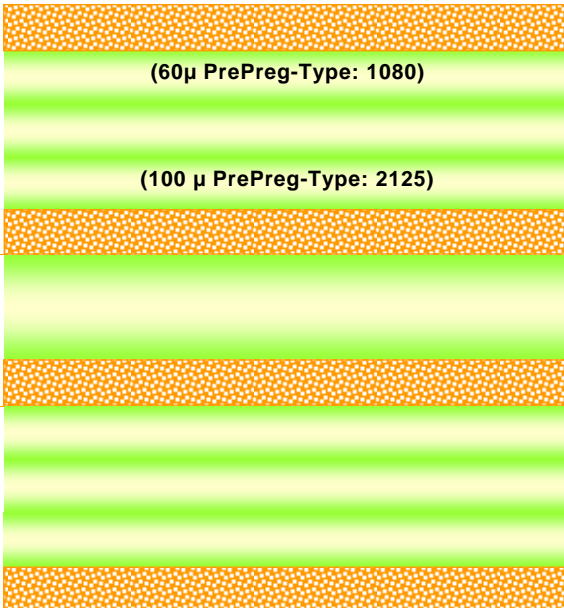
Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

| | | | | | | |
|----|-----|-----|----|--------|--------|----|
| 04 | 108 | FR4 | 35 | L50.35 | P10_06 | S1 |
|----|-----|-----|----|--------|--------|----|

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_108_FR4_35_L50.35_p10_06_s1

| Layers | in μ | Material | Build-Up | Assembly | |
|-----------------|-----------|----------|---|--|---|
| Layer-1 | 35 μ | Copper |  <p>(60μ PrePreg-Type: 1080)</p> <p>(100 μ PrePreg-Type: 2125)</p> |  | |
| | 60 μ | Prepreg | | | |
| | 60 μ | Prepreg | | | |
| | 100 μ | Prepreg | | | |
| Layer-2 | 35 μ | Copper |  | | |
| | 500 μ | L-FR4 | | | |
| Layer-3 | 35 μ | Copper | | |  |
| | 100 μ | Prepreg | | | |
| | 60 μ | Prepreg | | | |
| | 60 μ | Prepreg | | | |
| Layer-99 | 35 μ | Copper | |  | |

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